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Abstract of the Disclosure

A composition and method which is suitable to enhance the wetting of an electroplating bath solution on an electroplating surface. Optimum wetting of the electroplating bath solution to the electroplating surface results in an electroplated metal which is substantially devoid of surface pits and other structural defects and is characterized by enhanced gap fill capability. The composition includes a suppressor additive for the electroplating bath solution. The suppressor additive is a copolymer which includes various proportions of ethylene oxide monomer and propylene oxide monomer.